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BAP64-03

Silicon PIN diode

Rev. 8 — 12 May 2015

Product data sheet

1. Product profile

1.1 General description

Planar PIN diode in a SOD323 very small plastic SMD package.

1.2 Features and benefits



- High voltage, current controlled
- RF resistor for RF attenuators and switches
- Low diode capacitance
- Low diode forward resistance
- Low series inductance
- For applications up to 3 GHz
- AEC-Q101 qualified

1.3 Applications

- RF attenuators and switches

2. Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Symbol
1	cathode ^[1]		 sym006
2	anode		

[1] The marking bar indicates the cathode.

3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BAP64-03	-	plastic surface mounted package; 2 leads;	SOD323



4. Marking

Table 3. Marking

Type number	Marking code
BAP64-03	A3

5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	175	V
I_F	forward current		-	100	mA
P_{tot}	total power dissipation	$T_{sp} = 90\text{ °C}$	-	500	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-65	+150	°C

6. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		120	K/W

7. Characteristics

Table 6. Characteristics

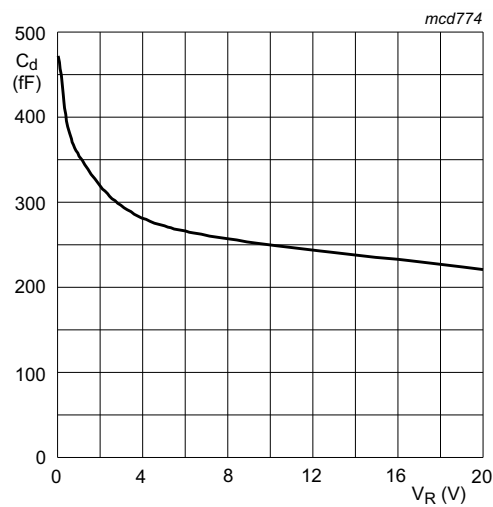
$T_j = 25\text{ °C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	$I_F = 50\text{ mA}$	-	0.95	1.1	V
I_R	reverse current	$V_R = 175\text{ V}$	-	-	10	μA
		$V_R = 20\text{ V}$	-	-	1	μA
C_d	diode capacitance	see Figure 1 ; $f = 1\text{ MHz}$;				
		$V_R = 0\text{ V}$	-	0.48	-	pF
		$V_R = 1\text{ V}$	-	0.35	-	pF
		$V_R = 20\text{ V}$	-	0.23	0.35	pF

Table 6. Characteristics ...continued $T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

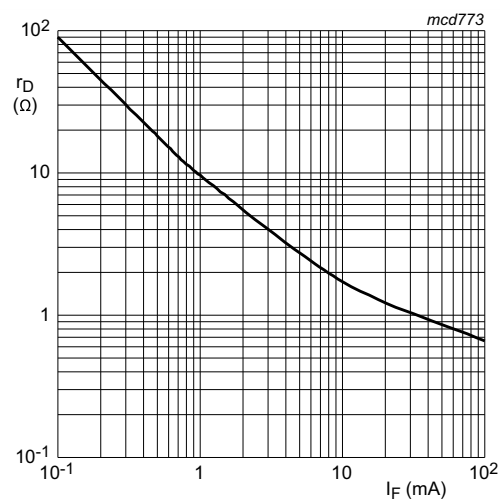
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
r_D	diode forward resistance	see Figure 2 ; $f = 100\text{ MHz}$; [1]				
		$I_F = 0.5\text{ mA}$	-	20	40	Ω
		$I_F = 1\text{ mA}$	-	10	20	Ω
		$I_F = 10\text{ mA}$	-	2.0	3.8	Ω
		$I_F = 100\text{ mA}$	-	0.7	1.35	Ω
τ_L	charge carrier life time	when switched from $I_F = 10\text{ mA}$ to $I_R = 6\text{ mA}$; $R_L = 100\text{ }\Omega$; measured at $I_R = 3\text{ mA}$	-	1.55	-	μs
L_S	series inductance		-	1.68	-	nH

[1] Guaranteed on AQL basis: inspection level S4, AQL 1.0.



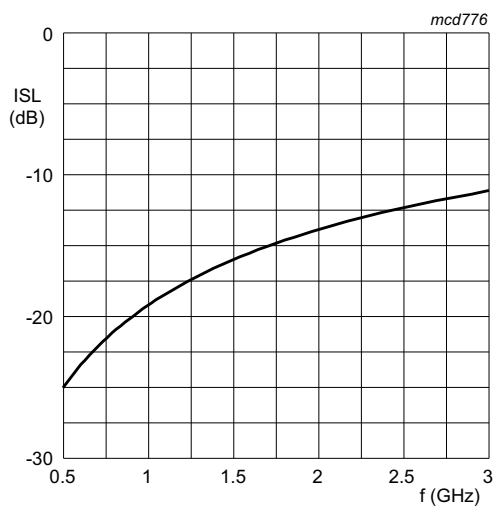
$f = 1\text{ MHz}$; $T_j = 25\text{ }^{\circ}\text{C}$.

Fig 1. Diode capacitance as a function of reverse voltage; typical values



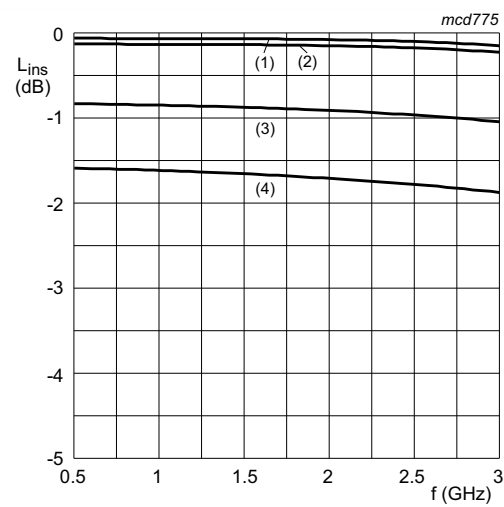
$f = 100\text{ MHz}$; $T_j = 25\text{ }^{\circ}\text{C}$.

Fig 2. Forward resistance as a function of forward current; typical values



$T_{amb} = 25\text{ }^{\circ}\text{C}$
Diode zero biased and inserted in series with a $50\text{ }\Omega$ stripline circuit

Fig 3. Isolation of the diode as a function of frequency; typical values



$T_{amb} = 25\text{ }^{\circ}\text{C}$
(1) $I_F = 100\text{ mA}$
(2) $I_F = 10\text{ mA}$
(3) $I_F = 1\text{ mA}$
(4) $I_F = 0.5\text{ mA}$
Diode inserted in series with a $50\text{ }\Omega$ stripline circuit and biased via the analyzer Tee network

Fig 4. Insertion loss of the diode as a function of frequency; typical values

8. Package outline

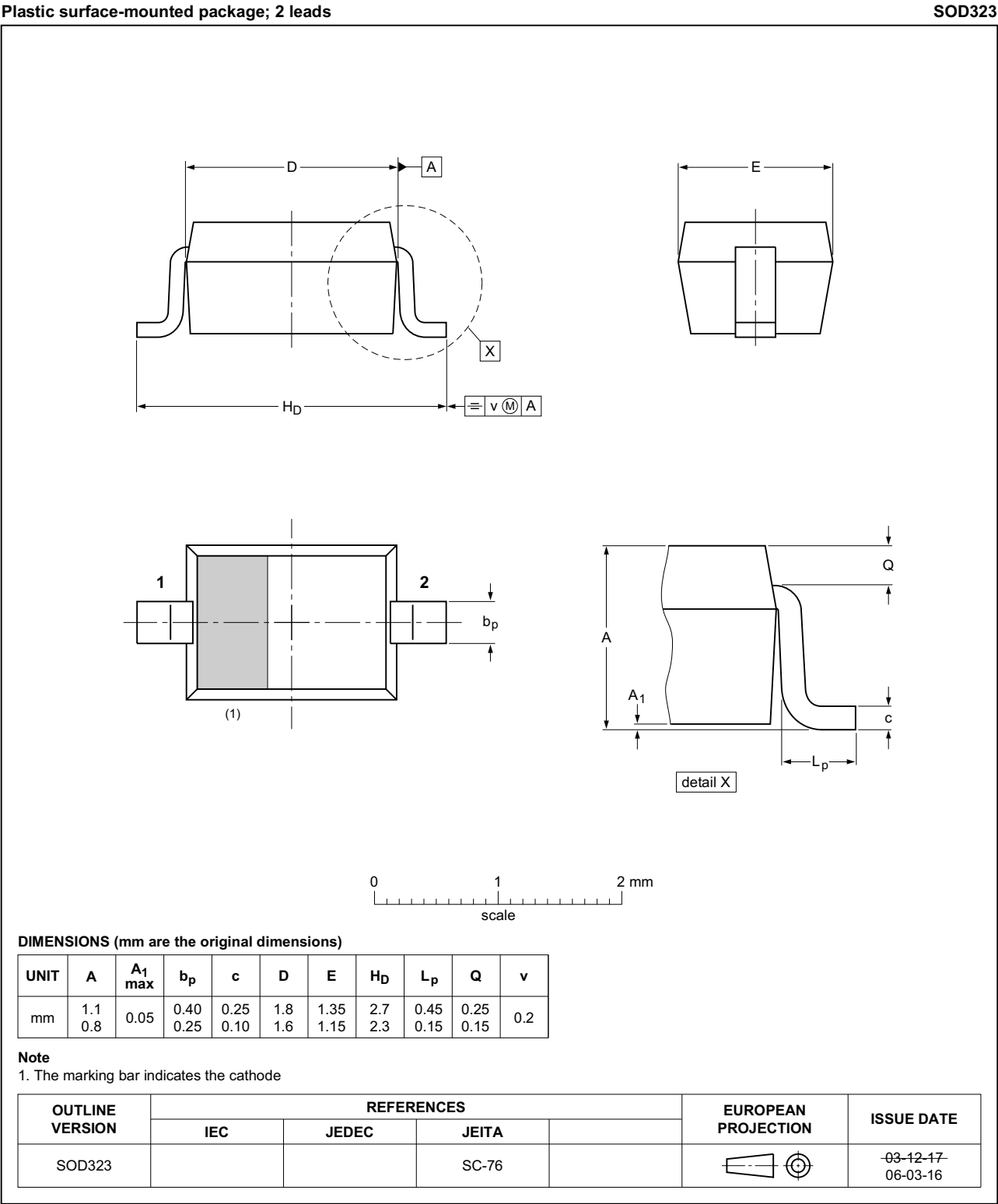


Fig 5. Package outline SOD323

9. Abbreviations

Table 7. Abbreviations

Acronym	Description
AQL	Acceptable Quality Level
PIN	P-type, Intrinsic, N-type
SMD	Surface Mounted Device
S4	Special inspection level 4

10. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP64-03 v.8	20150512	Product data sheet	-	BAP64-03 v.7
Modifications:	• AEC-Q101 qualified			
BAP64-03 v.7	20140428	Product data sheet	-	BAP64-03 v.6
BAP64-03 v.6	20140211	Product data sheet	-	BAP64-03 v.5
BAP64-03 v.5 (9397 750 12632)	20040211	Product specification	-	BAP64-03 v.4
BAP64-03 v.4 (9397 750 06279)	19990827	Product specification	-	BAP64-03_N v.3
BAP64-03_N v.3 (9397 750 06087)	19990616	Preliminary specification	-	BAP64-03 v.2
BAP64-03 v.2 (9397 750 05557)	19990510	Objective specification	-	BAP64-03_N v.1
BAP64-03_N v.1 (9397 750 05493)	19981204	Objective specification	-	-

11. Legal information

11.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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